

Title (en)

Process of grinding cutting tools

Title (de)

Verfahren zum Schleifen von Zerspanungswerkzeugen

Title (fr)

Procédé de meulage d'outils de coupe

Publication

EP 1834731 B1 20100512 (DE)

Application

EP 06405116 A 20060315

Priority

EP 06405116 A 20060315

Abstract (en)

[origin: EP1834731A1] The disc (1) has roof sides (3a,3b) including grinding layers, where straight and convex surface contour areas (13,15) of a chipping tool (11) with one of the roof sides and concave surface contour area (21) of the chipping tool with other roof side are ground. The disc is designed as a dual cone disc, where a rotation axis coincides with a cone axis. The roof sides are formed respectively on a plane, which is in an angle lesser than ninety degrees. An independent claim is also included for a method for grinding a chipping tool.

IPC 8 full level

B24B 3/00 (2006.01); **B24B 53/00** (2006.01)

CPC (source: EP US)

B24B 3/36 (2013.01 - EP US); **B24B 53/14** (2013.01 - EP US)

Citation (examination)

- GB 2289982 A 19951206 - TOKYO SEIMITSU CO LTD [JP]
- DE 19632463 A1 19970227 - MITSUBISHI ELECTRIC CORP [JP]

Cited by

CN107065768A

Designated contracting state (EPC)

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DOCDB simple family (publication)

EP 1834731 A1 20070919; **EP 1834731 B1 20100512**; AT E467482 T1 20100515; DE 502006006932 D1 20100624; JP 2007245337 A 20070927; US 2007232202 A1 20071004

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